12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250204002.1
Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet and additional BOM options for select devices
Change Notification / Sample Request

Date: February 05, 2025
To: MOUSER PCN

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250204002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA230AIRGTR	INA230AIRGTR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250204002.1	**PCN Date:**	February 05, 2025
Title:	Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet and additional BOM options for select devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	May 06, 2025	**Sample requests accepted until:**	April 06, 2025*

***Sample requests received after April 06, 2025 will not be supported.**

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the qualified HPA9 process technology, die revision, data sheet and BOM option for the device listed below.

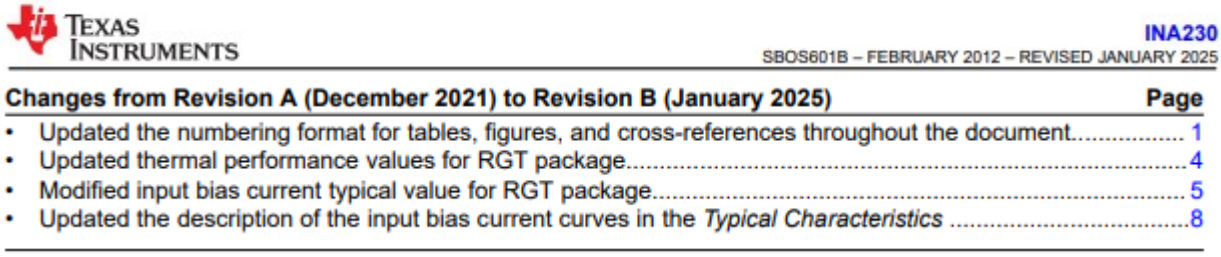
Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
DP1DM5	50HPA07	200 mm	RFAB	HPA9	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

	Current	Proposed
Wire diam/type	0.96mil Cu	0.80mil Cu

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



TEXAS INSTRUMENTS

INA230

SBOS601B – FEBRUARY 2012 – REVISED JANUARY 2025

Changes from Revision A (December 2021) to Revision B (January 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Updated thermal performance values for RGT package..... 4
- Modified input bias current typical value for RGT package..... 5
- Updated the description of the input bias current curves in the *Typical Characteristics* 8

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
INA230	SBOS601A	**SBOS601B**	http://www.ti.com/product/

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
A	**A**

Sample product shipping label (not actual product label)

Product Affected:

INA230AIRGTR

Qualification Report

Approve Date 10-January-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: INA230AIRGTR	Qual Device: INA230AIRGTT	QBS Reference: QPA1671IDCKR	QBS Reference: TPS54622RHLREP	QBS Reference: SN75DPHY440SSRHRR	QBS Reference: PGA900ARHHR	QBS Reference: LMK1D1204MRGTR	QBS Reference: INA226AQDGSRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-	3/231/0	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-	3/231/0	-	1/77/0
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	-	3/231/0	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-	-	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2397/0[1]	-	-	3/2400/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	-	1/22/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	-	-	1/10/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	3/9/0	-	-	1/3/0	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	3/9/0	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	3/18/0	-	-	1/3/0	-	1/3/0
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	3/90/0	-	-	1/30/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	-	-	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	-	-	3/90/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device INA230AIRGTR is qualified at MSL1 260C
Qual Device INA230AIRGTT is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.